

Appl. No. 10/505,287; Docket No. FR02 0010US
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Abstract

The present invention is used for the realization of wiring tracks, contact pads, and vias. Consistent with an example embodiment, there is a method of forming electrical connections on a substrate. The method comprises depositing an intermediate layer of material on a substrate. An etching mask having at least one window is formed. The layer of intermediate material is etched in conformity with the mask in order to form at least one aperture therein. In order to narrow the aperture, lateral side-walls of the aperture are coated with a spacer. So as to fill the narrowed aperture, at least one conductor material is deposited therein. So as to remove excess conductor material outside the aperture, an abrasion operation is performed.